

ANISOTROPIC ETCHING OF OPTICAL COMPONENTS

CROSS REFERENCE TO RELATED APPLICATIONS

This application is a continuation-in-part to U.S. Patent Application Serial No.

was abandoned

5 09/859,593, filed May 17, 2001.

This application claims priority to United States Provisional Patent Application

Serial Number 60/293,615, filed May 25, 2001.

This application claims priority to United States Provisional Patent Application
Serial Number 60/297,208, filed June 8, 2001.

10 Field of the Invention

This invention relates to integrated circuits, and more particularly to integrated circuits including both optical and electronic aspects.

Background of the Invention

In the electronic integrated circuit industry, there is a continuing effort to increase device speed and increase device densities. Optical systems are a technology that promise to increase the speed and current density of integrated circuits. Various components of optical and electronic integrated circuits can be discrete elements made from glass or clear plastic or alternatively can be formed from a semiconductor material, such as silicon.

The majority of the semiconductor industry efforts, including a massive number of person-hours of research and development, has focused its efforts on silicon-based electronic circuits in attempting to make electronic circuits faster and more reliable. While other semiconductor technologies such as Ga-As have shown great promise, the emphasis on the research in development in Silicon has reduced the rate of development of the other semiconductors. This concentration on silicon devices has been rewarded by quicker and more reliable silicon devices, however the rate improvement of silicon-based device speed